

3.2x2.4mm SMD CHIP LED LAMP

Part Number: APBD3224ESGC-F01

High Efficiency Red Super Bright Green

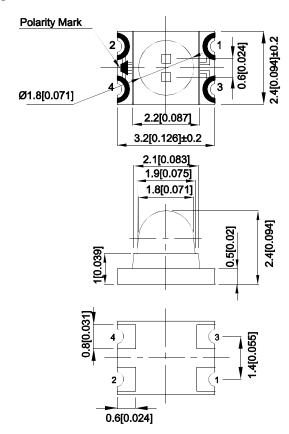
Features

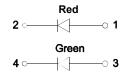
- 3.2x2.4mm SMD LED, 2.4mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Package: 1500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

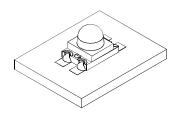
Descriptions

- The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.
- The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions









- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1 (0.004")$ unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAF1337 **REV NO: V.9A DATE: NOV/10/2015** PAGE: 1 OF 6 **APPROVED: Wynec CHECKED: Allen Liu** DRAWN: L.Q.Xie ERP: 1203000867

Selection Guide

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
APBD3224ESGC-F01	High Efficiency Red (GaAsP/GaP)	- Water Clear	30	70	- 20°
			*12	*40	
	Super Bright Green (GaP)		20	55	
			*20	*55	

- Notes:
 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity / luminous Flux: +/-15%.

 * Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red Super Bright Green	627 565		nm	I==20mA
λD [1]	Dominant Wavelength	High Efficiency Red Super Bright Green	617 568		nm	I==20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red Super Bright Green	45 30		nm	I==20mA
С	Capacitance	High Efficiency Red Super Bright Green	15 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red Super Bright Green	2 2.2	2.5 2.5	V	IF=20mA
lR	Reverse Current	High Efficiency Red Super Bright Green		10 10	uA	V _R = 5V

Notes:

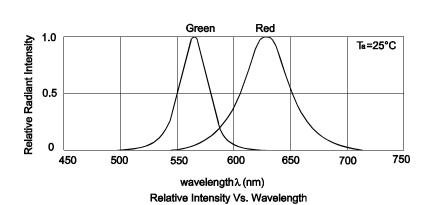
- 1. Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
- 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

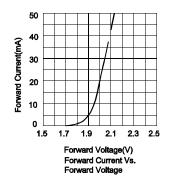
Parameter	High Efficiency Red	Super Bright Green	Units		
Power dissipation	75	62.5	mW		
DC Forward Current	30	25	mA		
Peak Forward Current [1]	160	140	mA		
Reverse Voltage		V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

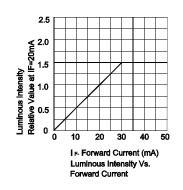
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

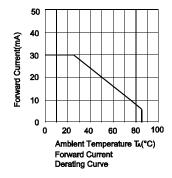
SPEC NO: DSAF1337 **REV NO: V.9A** DATE: NOV/10/2015 PAGE: 2 OF 6 APPROVED: Wynec **CHECKED: Allen Liu** DRAWN: L.Q.Xie ERP: 1203000867

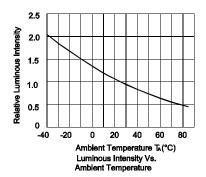


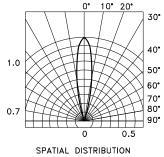
APBD3224ESGC-F01 High Efficiency Red





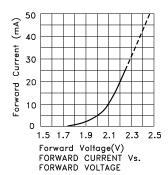


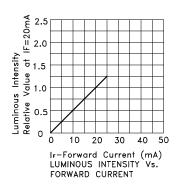


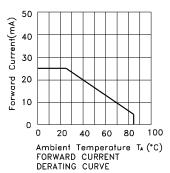


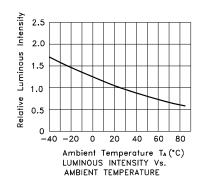
SPEC NO: DSAF1337 REV NO: V.9A DATE: NOV/10/2015 PAGE: 3 OF 6
APPROVED: Wynec CHECKED: Allen Liu DRAWN: L.Q.Xie ERP: 1203000867

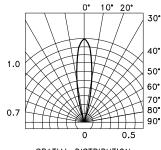
Super Bright Green











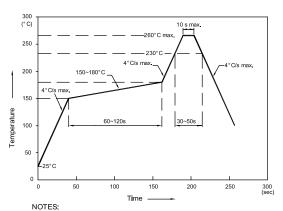
SPATIAL DISTRIBUTION

SPEC NO: DSAF1337 REV NO: V.9A DATE: NOV/10/2015 PAGE: 4 OF 6
APPROVED: Wynec CHECKED: Allen Liu DRAWN: L.Q.Xie ERP: 1203000867

APBD3224ESGC-F01

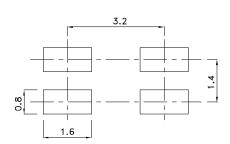
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



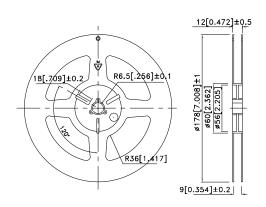
- 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed
- to high temperature.
 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



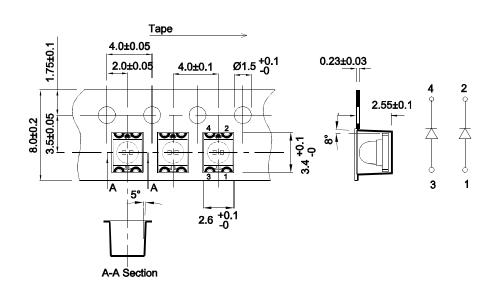
Tape Dimensions (Units : mm)

Reel Dimension



PAGE: 5 OF 6

ERP: 1203000867

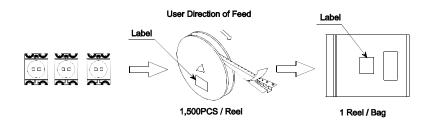


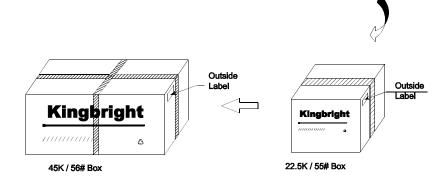
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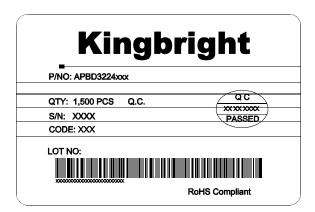
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PACKING & LABEL SPECIFICATIONS

APBD3224ESGC-F01







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 SPEC NO: DSAF1337
 REV NO: V.9A
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 PAGE: 6 OF 6

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